

COUNT	DESCRIPTION OF REVISIONS	BY	CHKD	DATE	COUNT	DESCRIPTION OF REVISIONS	BY	CHKD	DATE
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APPLICABLE STANDARD				
RATING	VOLTAGE	250 V AC	OPERATING TEMPERATURE RANGE	-30 °C TO +85 °C(NOTE1)
	CURRENT	AWG22 TO 26 : 2A	STORAGE TEMPERATURE RANGE	-10 °C TO +60 °C(NOTE2)
		AWG28 : 1A		
		AWG30 : 0.5A		

SPECIFICATIONS						
ITEM	TEST METHOD	REQUIREMENTS	QT	AT		
CONSTRUCTION						
GENERAL EXAMINATION	VISUALLY AND BY MEASURING INSTRUMENT.	ACCORDING TO DRAWING.	×	×		
MARKING	CONFIRMED VISUALLY.		×	×		
ELECTRIC CHARACTERISTICS						
CONTACT RESISTANCE	100 mA (DC OR 1000 Hz).	30 mΩ MAX.	×	—		
INSULATION RESISTANCE	500 V DC.	1000 MΩ MIN.	×	—		
VOLTAGE PROOF	650 V AC FOR 1 min.	NO FLASHOVER OR BREAKDOWN.	×	—		
MECHANICAL CHARACTERISTICS						
MECHANICAL OPERATION	50 TIMES INSERTIONS AND EXTRACTIONS.	① CONTACT RESISTANCE: 30 mΩ MAX. ② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	×	—		
VIBRATION	FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE 0.75 mm, AT 2 h, FOR 3 DIRECTIONS.	① NO ELECTRICAL DISCONTINUITY OF 1 μs.	×	—		
SHOCK	490 m/s ² DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.	② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	×	—		
ENVIRONMENTAL CHARACTERISTICS						
RAPID CHANGE OF TEMPERATURE	TEMPERATURE -55 →5 TO 35 →+85 →5 TO 35 °C TIME 30 →10 TO 15 →30 →10 TO 15min UNDER 5 CYCLES.	① CONTACT RESISTANCE: 30 mΩ MAX. ② INSULATION RESISTANCE: 1000 MΩ MIN. ③ NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	×	—		
DAMP HEAT (STEADY STATE)	EXPOSED AT 40 ± 2 °C, 90 ~ 95 %, 96 h.	① CONTACT RESISTANCE: 30 mΩ MAX. ② INSULATION RESISTANCE: 500 MΩ MIN. ③ NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	×	—		
RESISTANCE TO SOLDERING HEAT	1) AUTOMATIC SOLDERING (REFLOW) 《REFLOW AREA》 MAX 240°C WITHIN 10 sec. MIN 220°C 10 sec to 30 sec. 《PREHEATING AREA》 150°C to 160 °C 100 sec. To 120 sec. PUT THROUGH IN REFLOW FURNACE TWICE. LEAVE IN AMBIENT TEMPERATURE AND HUMIDITY FOR 1 HOUR. CONNECTOR TEMPERATURE TO BE AMBIENT FOR SECOND REFLOW. 2) MANUAL SOLDERING SOLDERING IRON TEMPERATURE : 290±10°C, SOLDERING TIME : 3 sec. NO STRENGTH ON CONTACT.	NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.	×	—		
SOLDERABILITY	SOLDERING TEMPERATURE : 230±5°C SOLDERING TIME : 3 sec.	A NEW UNIFORM COATING OF SOLDER SHALL COVER MINIMUM OF 95 % OF THE SURFACE BEING IMMersed.	×	—		
REMARKS NOTE1:INCLUDING THE TEMPERATURE RISE BY CURRENT. NOTE2:APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFORE PCB ON BOARD, AFTER PCB BOARD,OPERATING TEMPERATURE AND HUMIDITY RANGE IS APPLIED FOR INTERIM STORAGE DURING TRANSPORTATION. Unless otherwise specified, refer to MIL-STD-1344.		DRAWN T.YAMAMOTO '01. 8.30	DESIGNED T.Yamamoto 6/1 8.30	CHECKED T.Miyazaki 6/1. 8.3/	APPROVED K.Katayama '01.9.3	RELEASED
Note QT:Qualification Test AT:Assurance Test ×:Applicable Test						
HS HIROSE ELECTRIC CO., LTD.		SPECIFICATION SHEET		PART NO. DF11C-20DP-2V (57)		
CODE NO.(OLD) CL		DRAWING NO. ELC4-071162-01		PART NO. CL543-0690-0-57		1/1

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